

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jun Jung Kim</td> <td>02/28/2007</td> </tr> <tr> <td>Young Gun Ko</td> <td>02/28/2007</td> </tr> <tr> <td>Jae-Eun Park</td> <td>02/28/2007</td> </tr> </tbody> </table>		Name	Execution Date	Jun Jung Kim	02/28/2007	Young Gun Ko	02/28/2007	Jae-Eun Park	02/28/2007
Name	Execution Date								
Jun Jung Kim	02/28/2007								
Young Gun Ko	02/28/2007								
Jae-Eun Park	02/28/2007								
RECEIVING PARTY DATA									
Name:	SAMSUNG ELECTRONICS CO. LTD.								
Street Address:	416 MAETAN-DONG, YEONGTONG-GU								
City:	SUWON-SI, GYEONGGI-DO								
State/Country:	KOREA, REPUBLIC OF								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11693254</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11693254				
Property Type	Number								
Application Number:	11693254								
CORRESPONDENCE DATA									
Fax Number:	(845)892-6363								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	845-894-8469								
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Correspondent Name:	International Business Machines Corp.								
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Address Line 4:	Hopewell Junction, NEW YORK 12533								
ATTORNEY DOCKET NUMBER:	FIS920060245US1								
NAME OF SUBMITTER:	Yuanmin Cai								
Total Attachments: 3 source=FIS920060245US1_SamsungAssignment#page1.tif source=FIS920060245US1_SamsungAssignment#page2.tif source=FIS920060245US1_SamsungAssignment#page3.tif									

CH \$40.00 11693254

PATENT ASSIGNMENT FORM

For and in consideration of good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor acknowledges his/her prior and ongoing obligation to sell, assign, and transfer, and agrees to sell, assign, and transfer the entire world wide right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements conceived during and within the scope of his/her employment, and further acknowledges that he/she has sold, assigned, and transferred, and hereby sells, assigns, and transfers, unto:

**SAMSUNG ELECTRONICS CO. LTD.
416 MAETAN-DONG, YEONGTONG-GU
SUWON-SI, GYEONGGI-DO
REPUBLIC OF KOREA**

a corporation of Republic of Korea, and SAMSUNG ELECTRONICS CO., LTD. desires to acquire all right, title, and interest, in and to the certain inventions (identified below), applications, and any United States and foreign patents to be obtained therefor relating to:

Title of Invention for United States Patent

OVERLAPPED STRESSED LINERS FOR IMPROVED CONTACTS

As set forth in United States Patent Application executed by each undersigned inventor on the date indicated by each inventor's signature below, and further identified by **Attorney Docket Number FIS920060245US1**;
(select one): executed concurrently herewith or Serial No. _____ Filed on _____

for and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States and foreign patents and all rights of priority to be obtained therefor which may issue on any such application or for said invention therein disclosed, including any and all reissues or extensions thereof, to be held and enjoyed by, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each undersigned inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to SAMSUNG ELECTRONICS CO., LTD., its successors and assigns, in accordance herewith;

Each undersigned inventor warrants and covenants that he/she has the full and unencumbered right to sell and assign the interests hereby sold and assigned and that he/she has not executed and will not execute any document or instrument in conflict herewith;

Each undersigned inventor further covenants and agrees that he/she, upon the request and at the expense of SAMSUNG ELECTRONICS CO., LTD., will execute and deliver any papers, make all rightful oaths, testify in any legal proceeding relating to said inventions and improvements, communicate to SAMSUNG ELECTRONICS CO., LTD. all facts known to the undersigned relating to such inventions and improvements and the history thereof; and perform all other lawful acts deemed necessary or desirable by SAMSUNG ELECTRONICS CO., LTD., and its legal representatives, to secure, maintain, and enforce patent protection for such inventions and improvements and for vesting title to such inventions and improvements in SAMSUNG ELECTRONICS CO., LTD., and in particular to perfect title to said above-identified certain inventions, and applications including divisions and continuations thereof, and any and all Letters Patent which may be granted therefor or thereon, including reissues, extensions, or counterparts;

Each undersigned inventor hereby grants to SAMSUNG ELECTRONICS CO., LTD. the power to insert in this Assignment any further identification which may be necessary or desirable for recordation of this Assignment.

Executed by Inventor 1 of 3

Signature: _____ Date: _____
Jun Jung Kim

Executed by Inventor 2 of 3


Signature: _____ Date: _____
Young Gun Ko

Executed by Inventor 3 of 3

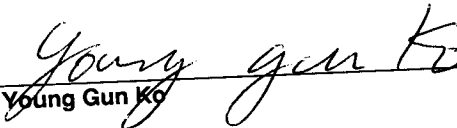
Signature: Jae E. Park Date: 2 / 28 / 2007
Jae-Eun Park

PATENT DOCKET NO. FIS920060245US1

Executed by Inventor 1 of 3

Signature:  Date: Feb 28th 2007
Jun Jung Kim

Executed by Inventor 2 of 3

Signature:  Date: Feb 28th 2007
Young Gun Ko

Executed by Inventor 3 of 3

Signature: _____ Date: _____
Jae-Eun Park